

IoT SuperServer SYS-211SE-31DS



More details here

Key Applications

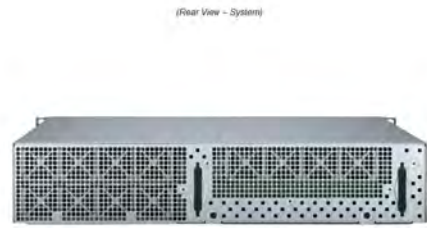
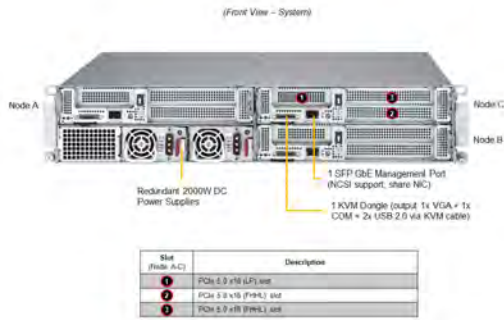
Multi-Access Edge Computing, Flex-RAN, Open-RAN vBBU, Telecom DRAN, CRAN, and Edge Core Application, Enterprise Edge Computing,

Key Features

- Single Socket E (LGA-4677) 4th Gen Intel® Xeon® Scalable processor (per node);
- 8 DIMMs; Up to 2TB 3DS ECC DDR5-4800: RDIMM/LRDIMM (per node);
- 2 PCIe Gen5 x16 FHHL slot and 1 PCIe Gen5 x16 HHHL slot (per node);
- 2 NVMe M.2 2280/22110 (per node);
- 4 counter-rotated fan speed control (per node); 1 Air Shroud (per node);
- Front-access 1+1 Redundant 2000W DC Power Supplies (per system);



Form Factor	2U Rackmount Enclosure: 449 x 88 x 430mm (17.7" x 3.5" x 16.9") Package: 750 x 240 x 590mm (29.5" x 9.5" x 23.2")
Processor	4th Gen Intel® Xeon® Scalable processors Single Socket LGA-4677 (Socket E) supported (CPUs (air cooled) with TDP over 205W are only supported under specific conditions. Contact customer support for details.)
System Memory	8 DIMM slots Up to 2TB ECC RDIMM/LRDIMM, DDR5-4800MHz
Drive Bays	2 M.2 NVMe M-Key, 2280/22110
Expansion Slots	1 PCIe 5.0 x16 LP slot(s) 2 PCIe 5.0 x16 FHHL slot(s)
On-Board Devices	Chipset: Intel® C741 Network Connectivity: 1x 1GbE SFP IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	LAN: 1 SFP GbE LAN port (shared with IPMI) Video: 1 VGA port(s) Serial Port: 1 COM Port(s) (1 COM COM port through KVM cable (from KVM dongle))



Slot (Rear A-C)	Description
1	PCIe 5.0 x16 (LP) slot
2	PCIe 5.0 x16 (Full) slot
3	PCIe 5.0 x16 (Full) slot

System Cooling	4 heavy duty fan(s) 4 heavy duty fan(s)
Power Supply	2000W Redundant DC -48V Power Supplies with PMBus Dimension (W x H x L): 73.5 x 40 x 265 mm
Management	IPMI 2.0; SuperDoctor® 5
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU thermal trip support, PEPI
Dimensions and Weight	Height: 3.5" (88 mm) Width: 17.7" (449 mm) Depth: 16.9" (430 mm) Gross Weight: 70.6 lbs (32 kg) Net Weight: 55.1 lbs (25 kg) Packaging: 9.5" (H) x 29.5" (W) x 23.2" (D) Available Color: Silver
Operating Environment	Operating Temperature: 0°C ~ 35°C (32°F ~ 95°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X13SEED-SF
Chassis	CSE-SE201-R2K06P